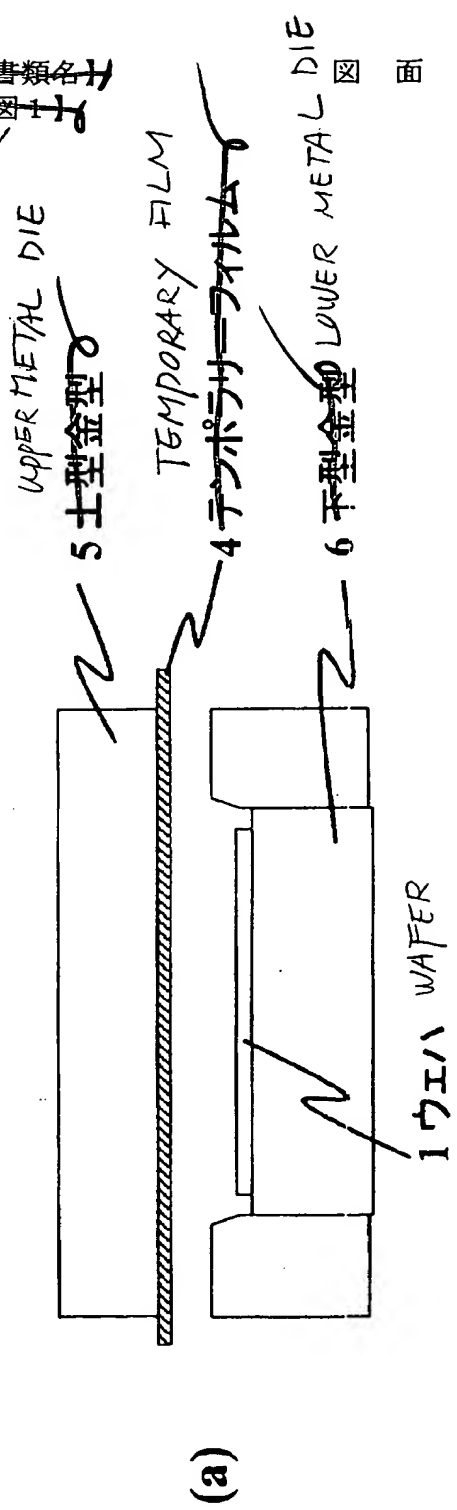
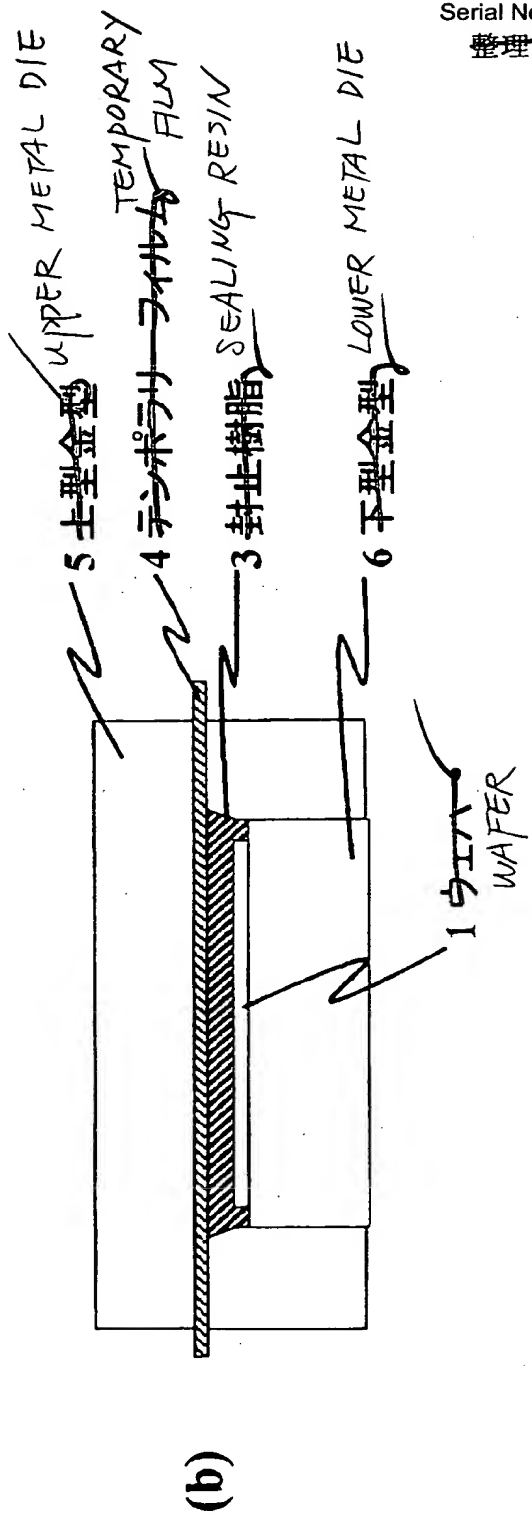


Fig. 1
【書類名】
【図】

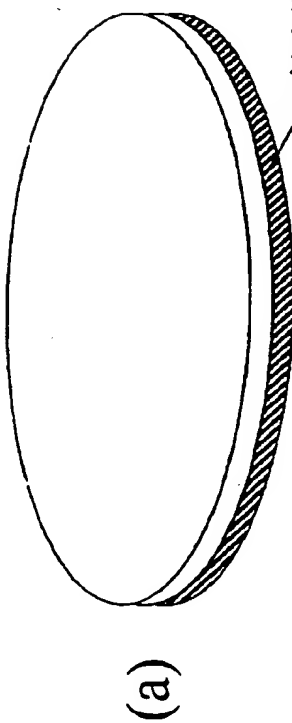
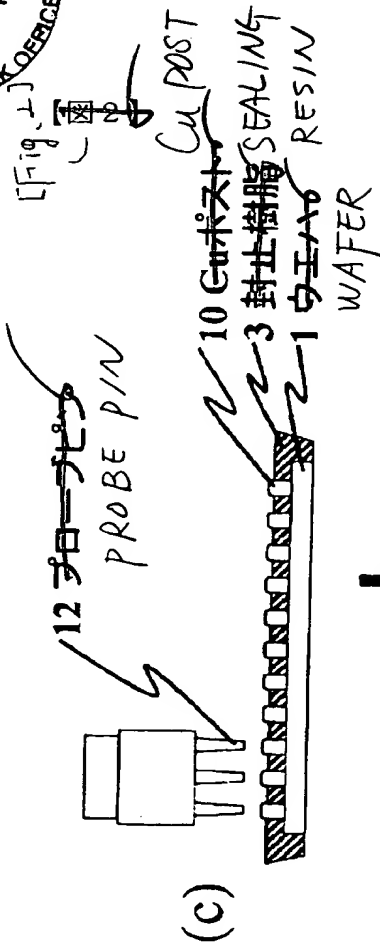


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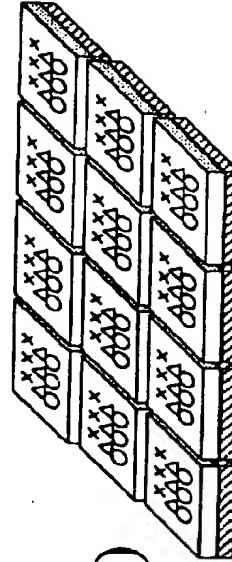
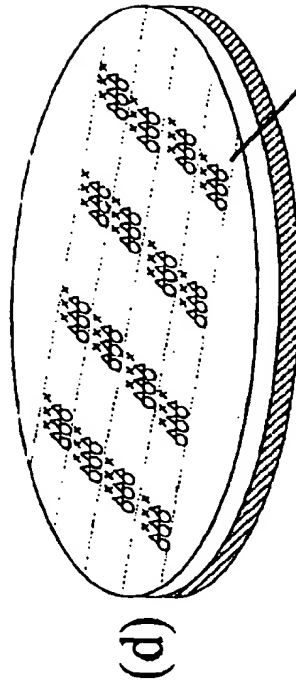
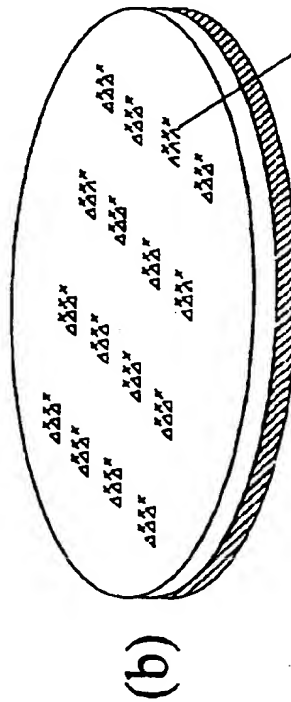


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整理番号: 00-40650

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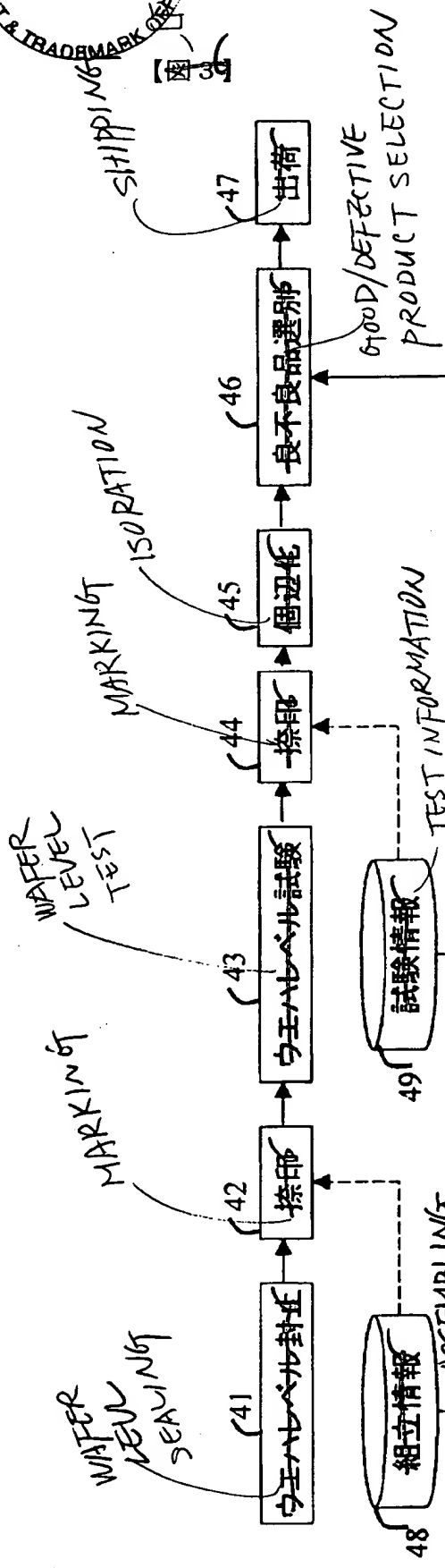


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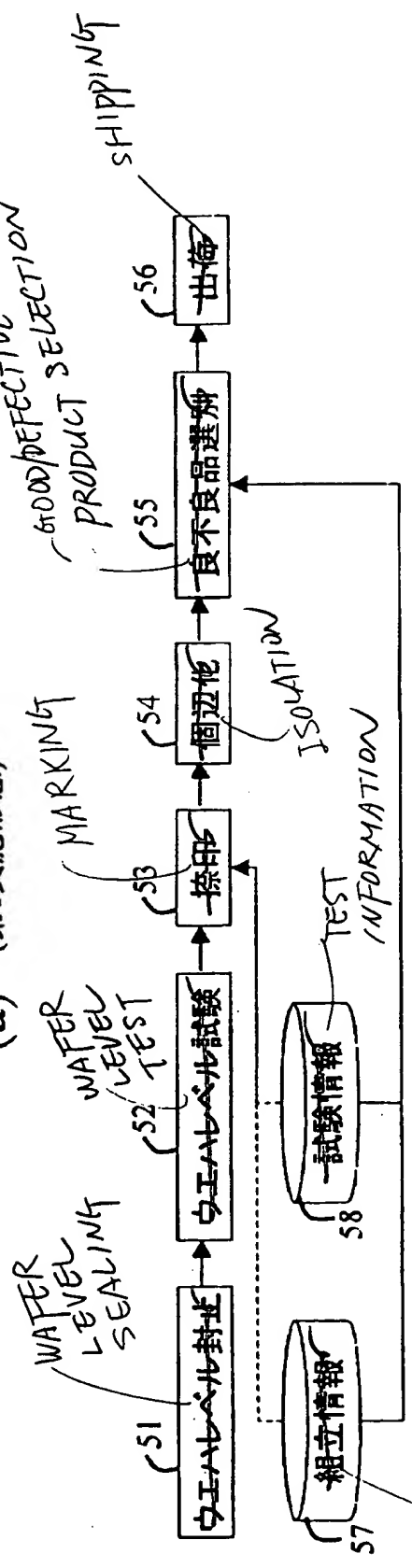
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(a) (第1実施形態) FIRST EMBODIMENT



(b) (第2実施形態) SECOND EMBODIMENT

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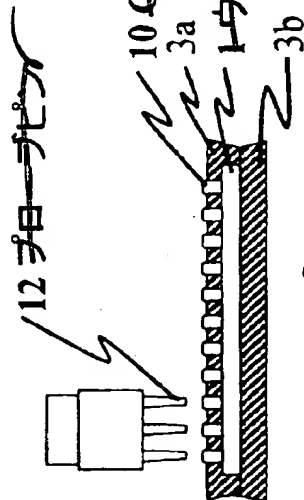
[Fig. 4]



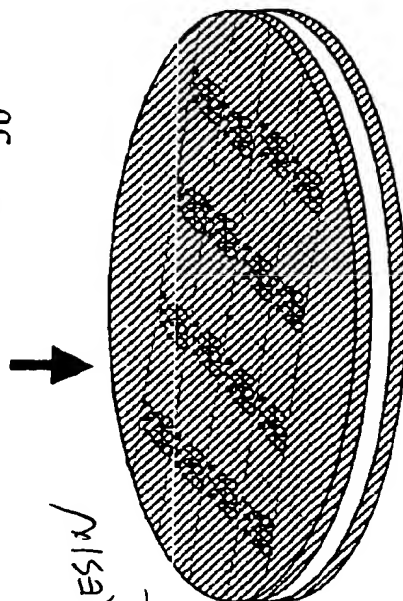
Serial No. 09/686,958
整理番号: 00-40650

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MPT
9/30/02

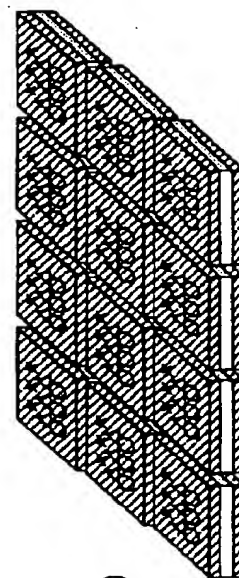
PROBE PIN



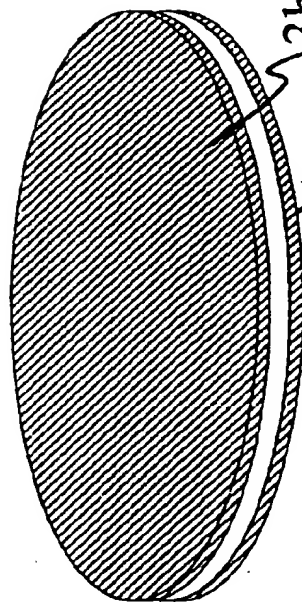
(c)



(d)



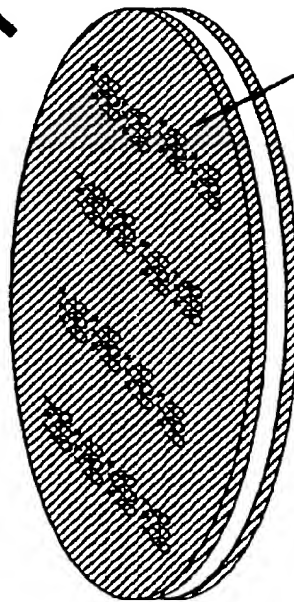
(e)



(a)

SEALING RESIN
封止樹脂

3b
3a



(g)

2 捺印
MARKING

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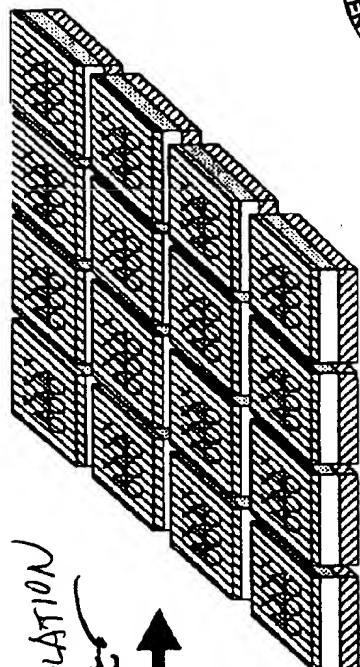
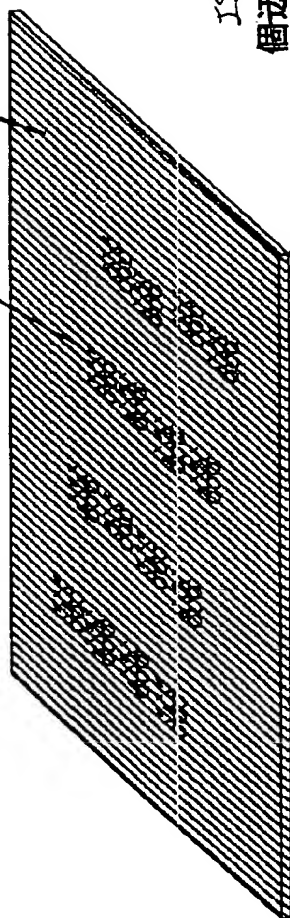
[Fig. 5]

図5

INFORMATION

MARKING
MANUFACTURING
捺印製造情報

7 樹脂シート
RESIN SHEET



ISOLATION
個辺化

3a 封止樹脂
SEALING RESIN

4a 半導体
WAFER



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